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## Product Change Notification

1. ECR #: 186946  
Notification #: 482

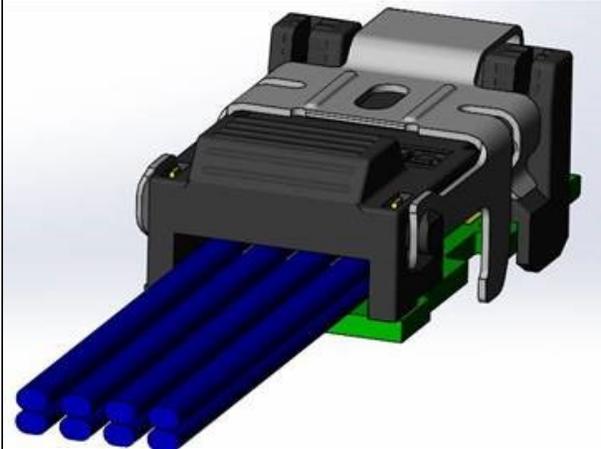
2. Date of Announcement: November 08, 2019

3. Series:  
• ECUE - ECUE

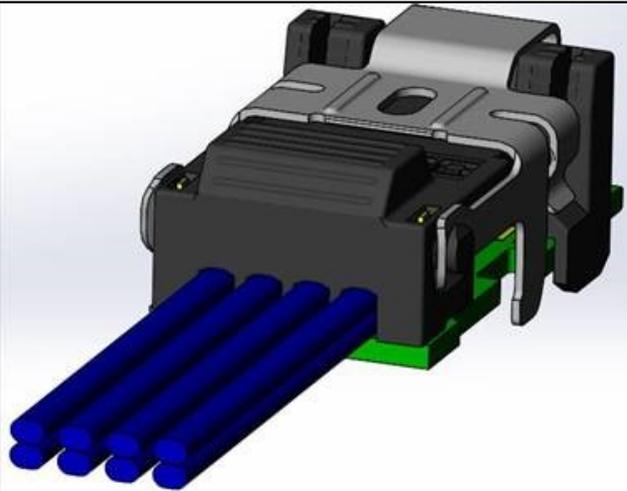
4. Part #'s Affected  
• ECUE-XX-XXX-XX-XX-XX-1-XX  
• ECUE-XX-XXX-XX-XX-XX-2-XX

5. Description of Change:  
On applicable 8-pair discrete wire twinax ECUE assemblies with low profile cap components, Samtec is improving the component cap design surrounding the component cables. On all ECUE assemblies, Samtec has made improvements to the plating process of the component PCB.

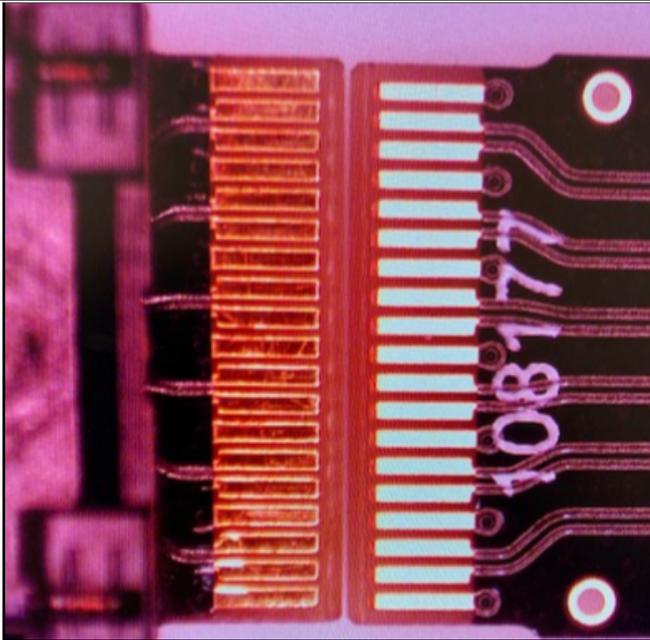
6. Method of Identifying Change  
For applicable 8-pair discrete wire twinax, low profile cap assemblies, the opening on the back of the cap has been reduced and modified to surround and secure the cables. On all ECUE assemblies, the plating process improvement may vary the reflection of the Gold plating surfaces.



This is an image of the current low profile cap installed on a discrete wire cable assembly.



This is an image of the modified cap on the discrete wire cable assembly, with the opening around the cables reduced to better surround the individual cables.



The PCB on the right is representative of the improved plating process, which may reflect light differently than the old process, represented by the PCB on the left. Differences may be seen at greater than 10x magnification and with varying lighting environments.

#### **7. Reason for Change:**

The modified cap design is a process improvement for discrete cable assemblies to aid in individual cable strain relief. In a discrete cable application, it is easier to apply higher strain to an individual cable component than it is in a ribbonized cable, so the cap helps to absorb this individual strain through interaction with the cable jacket. Testing has been performed to verify the increased individual cable retention as compared to the traditional cap design. The PCB plating process has been improved on all ECUE applications to improve electro-mechanical performance and consistency. The new design and its performance have been verified and validated by testing and through use in similar products. Both of the improvements described are compatible with all cable applications and will not affect the ability to install or remove the cable.

#### **8. Impact of Change on Form, Fit, or Function:**

- Form - The modification to the cap can be visually seen around the component cables, but the housing does not grow externally to cause any concerns with cable use.
- Form - The improved plating process can result in a different reflection of light in certain lighting environments and under greater than 10x magnification.

#### **9. Projected Implementation Date:** February 06, 2020

## **Disclaimer**

Please review the change notification details listed above for specific information regarding the nature and timing of the change. While Samtec has taken precautions to ensure this change is not detrimental to your application, each application can be unique and therefore customers should consider the effect of the change on their specific application.

Samtec has taken efforts to ensure that all users of this product who have requested change notifications have been informed. However, you should assume that this is the only notification that will be sent and you, as the recipient, must determine how to communicate this information to your organization(s) and customer(s) as appropriate. If you wish to opt out of receiving Samtec Engineering Change Notification emails, please contact [CustomerECN@samtec.com](mailto:CustomerECN@samtec.com). Due to technical progress, specifications are subject to change without notification and it is recommended to provide an alternative contact when opting out.

Please contact Samtec at [CustomerECN@samtec.com](mailto:CustomerECN@samtec.com) for any questions related to this change.